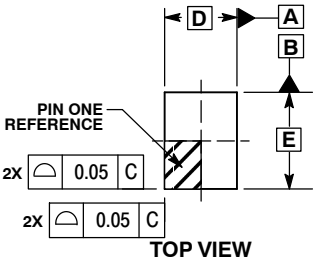
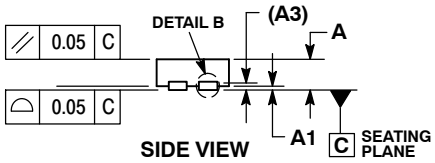
UDFN4 1.2x1.6, 0.5P
CASE 517CE
ISSUE B

DATE 03 APR 2012

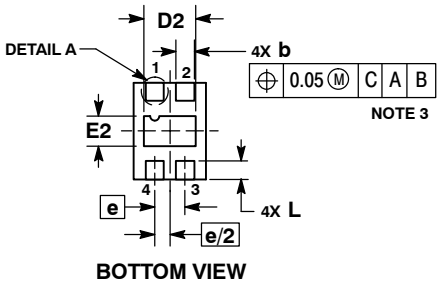
SCALE 4:1



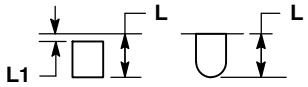
TOP VIEW



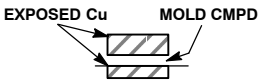
SIDE VIEW



BOTTOM VIEW



DETAIL A
ALTERNATE TERMINAL CONSTRUCTIONS



DETAIL B
ALTERNATE CONSTRUCTION

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 mm FROM THE TERMINAL TIPS.
4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

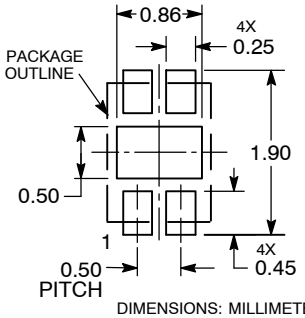
	MILLIMETERS		
DIM	MIN	NOM	MAX
A	0.45	0.50	0.55
A1	0.00	---	0.05
A3		0.13 REF	
b	0.25	0.30	0.35
D		1.20 BSC	
D2	0.76	0.86	0.96
E		1.60 BSC	
E2	0.40	0.50	0.60
e		0.50 BSC	
L	0.20	0.30	0.40
L1	---	---	0.15

GENERIC MARKING DIAGRAM*

XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

RECOMMENDED MOUNTING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY B. MARQUIS.	31 JAN 2012
A	ADDED GENERIC MARKING DIAGRAM. REQ. BY B. MARQUIS.	09 FEB 2012
B	CORRECTED SOLDERING FOOTPRINT AND MARKING DIAGRAM. REQ. BY B. MARQUIS.	03 APR 2012